DOCUMENT CHANGE REQUEST

DCR number 846	Changes required for: General	Originator: Alain Mouton
Date: 2014/10/13	Date sent: 2014/03/04	Organisation: Astrium
Status: IMPLEMENTED		

Title:	Generic Specification for Discrete Microwave Semiconductor Components		
Number:	5010	Issue:	1

Other documents affected:

Page:

22, 23 and 24

Paragraph:

charts III(a) and III(b)

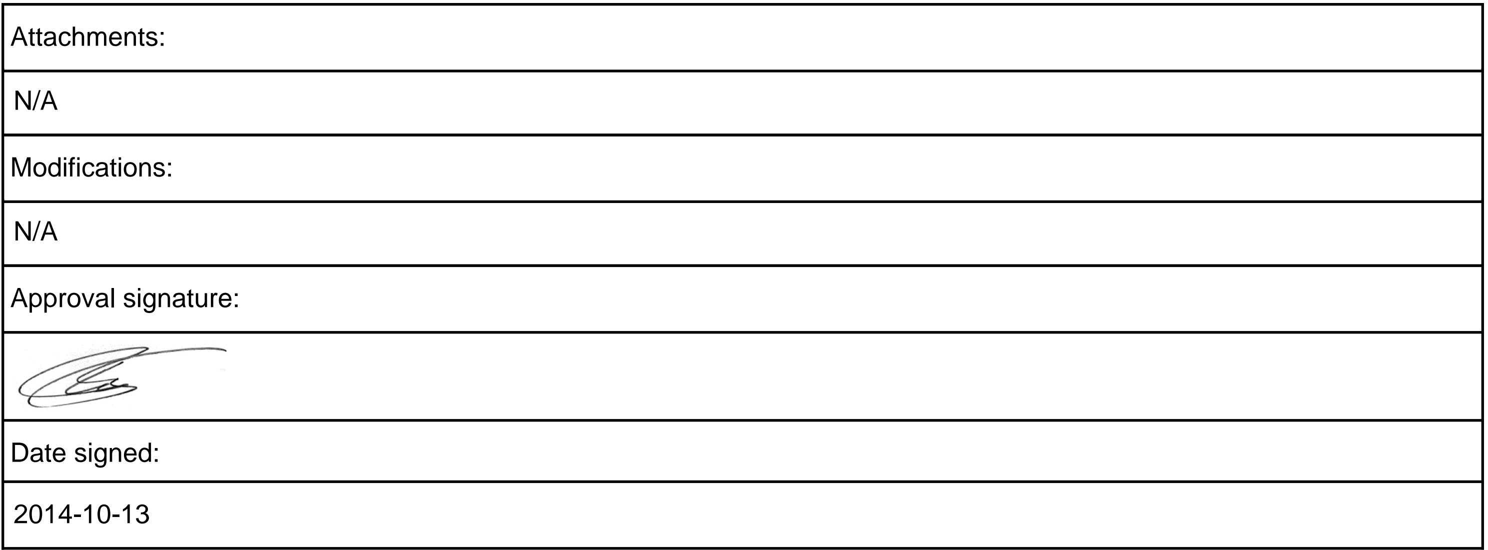
Original wording:

Proposed wording:

As for ESCC 5000 (DCR 147) and ESCC 9000 (DCR 148), in charts III(a) and III(b), a box "Hot Solder Dip (if applicable)" shall be added after "Electrical Measurements at Room Temperature" and before "Electrical Measurements at High and Low Temperatures".

In page 24, a note (8) shall be added stipulating "For components with hot solder dip final lead finish, the hot solder dip processing shall be performed at any time prior to High an Low Temperatures Electrical Measurements during Screening Tests. The requirements for hot solder dip are specified in ESCC Basic Specification No. 23500.

Justification:



Attachments:
N/A
Modifications:
N/A
Approval signature:
Date signed:
2014-10-13